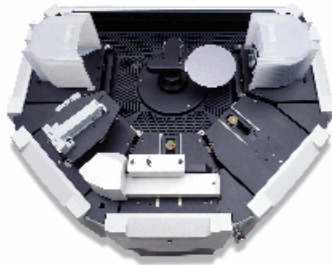


ADE 9350 UltraScan



- *UltraScan 9350 wafer thickness metrology system*

Product Highlights:

- The standard for **incoming wafer quality control**
- Dimensional measurements, resistivity and typing in one tool
- Wide variety of options including fully automated calibration
- Compact footprint

ADE's UltraScan 9350 with E-Plus Gage technology is the industry standard for 250 nm wafer geometry characterization. It meets SIA performance requirements for 250 nm design rule site flatness and edge exclusion. With standard resistivity and optional type gauges, the 9650 completely characterizes wafer quality for silicon manufacturers and IC fabs.

Incoming Quality Control

The clustered design of the 9350 enables sampling of wafer dimension, shape, flatness, resistivity and type in one metrology step. Options include fully automated calibration, adaptive SMIF and SECS interface. AGV compatible load stations can also be added to facilitate factory automation.

Using ADE's industry standard measurements, the 9350 can identify out of specification wafers before they cause yield loss in downstream processes. Material quality can be monitored.

Silicon Manufacturing

Using industry standard E-Plus Gage technology, the UltraScan 9350 characterizes wafers for 250 nm and greater line widths. The increased accuracy and repeatability of the 9350 translates into higher yields at final inspection. Compared to the UltraScan 9300 with **five cassette stations**, the compact, two cassette station design of the 9550 saves valuable floor space.

Programmable Resistivity Measurements

Non-contact resistivity measurements are taken in parallel with standard dimensional measurements, improving throughput. Users can program the system to determine resistivity at any point on the surface and in high or low ranges. Non-contact wafer typing is also available.